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(12) **United States Design Patent** (10) **Patent No.:** **US D824,969 S**  
**Alfaro et al.** (45) **Date of Patent:** **\*\* Aug. 7, 2018**

(54) **CERAMIC BONDING TOOL WITH TEXTURED TIP**

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(\*\*) Term: **15 Years**

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(21) Appl. No.: **29/612,580**

(57) **CLAIM**

The ornamental design for a ceramic bonding tool with textured tip, as shown and described.

(22) Filed: **Aug. 2, 2017**

**DESCRIPTION**

**Related U.S. Application Data**

(62) Division of application No. 29/516,521, filed on Feb. 3, 2015, now Pat. No. Des. 797,826.

(51) **LOC (11) Cl.** ..... **15-09**

(52) **U.S. Cl.**  
USPC ..... **D15/144**

(58) **Field of Classification Search**  
USPC ..... D8/14, 14.1, 29, 29.1, 29.2, 30;  
D15/122, 138, 144, 144.1, 144.2;

(Continued)

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FIG. 1 depicts a perspective view of a ceramic bonding tool with textured tip.

FIG. 2 depicts a side elevation view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 3 depicts a top plan view of the ceramic bonding tool with textured tip of FIG. 1.

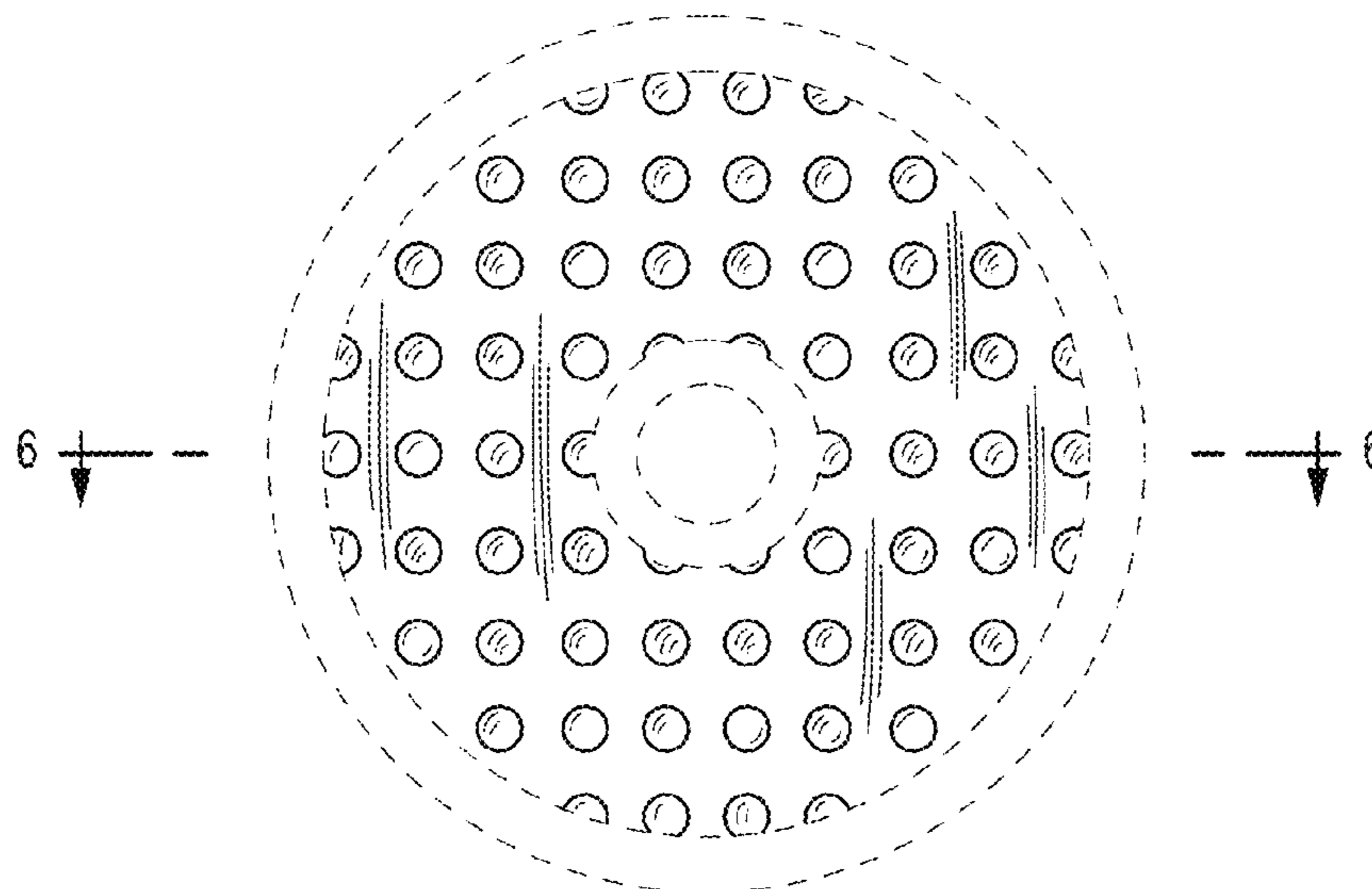
FIG. 4 depicts a bottom plan view of the ceramic bonding tool with textured tip of FIG. 1.

FIG. 5 depicts a detailed bottom plan view of the ceramic bonding tool with textured tip shown in FIG. 4; and,

FIG. 6 depicts a detailed side cross-section view of the ceramic bonding tool with textured tip, the cross-section taken along cross-section indicator line 6-6 of FIG. 5.

The broken lines in the drawings illustrate environmental structure on the article and form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**



- (58) **Field of Classification Search**  
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 CPC .. B23K 20/004; B23K 20/005; B23K 20/106;  
 H01L 24/85  
 See application file for complete search history.

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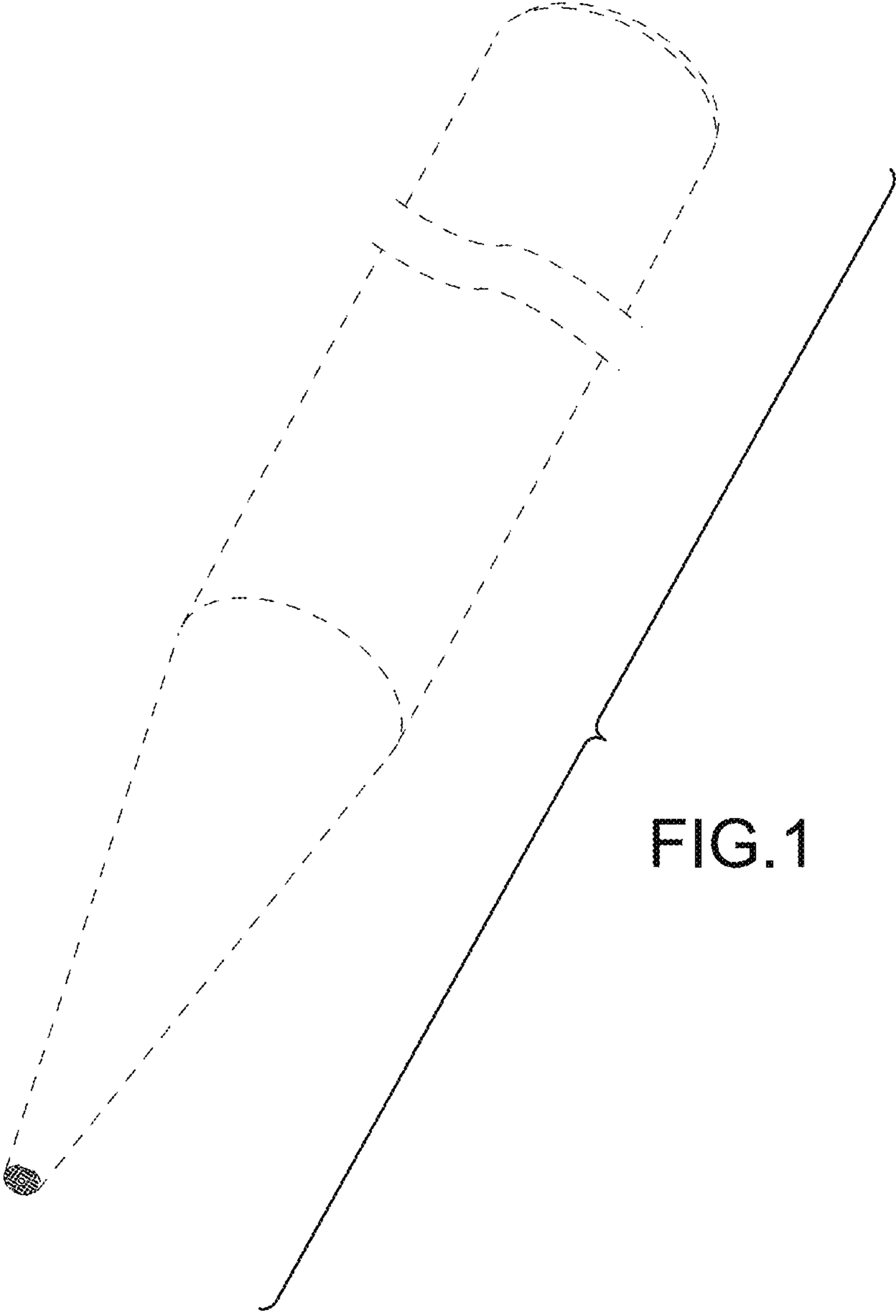


FIG. 1

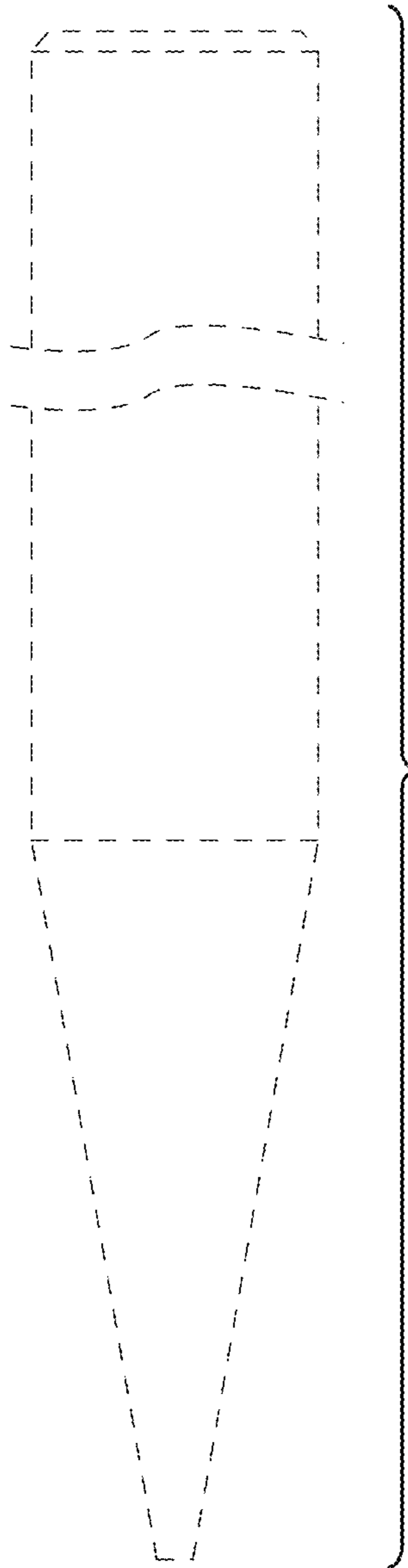


FIG. 2

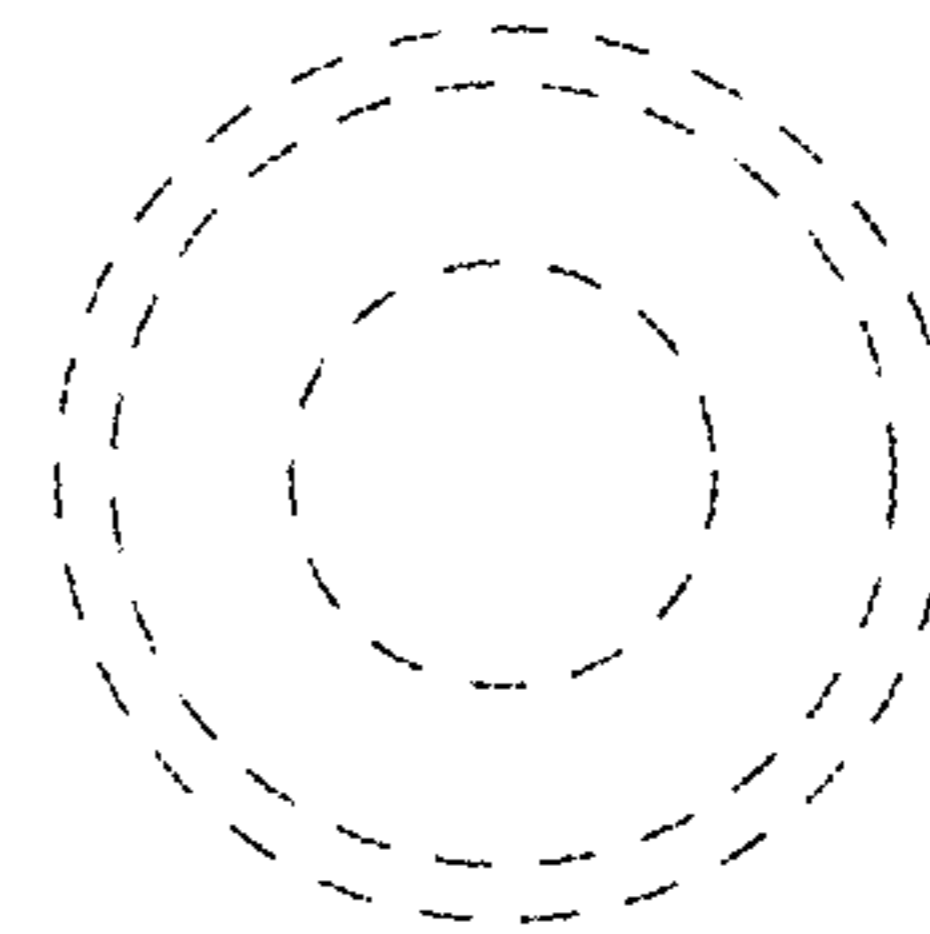


FIG. 3

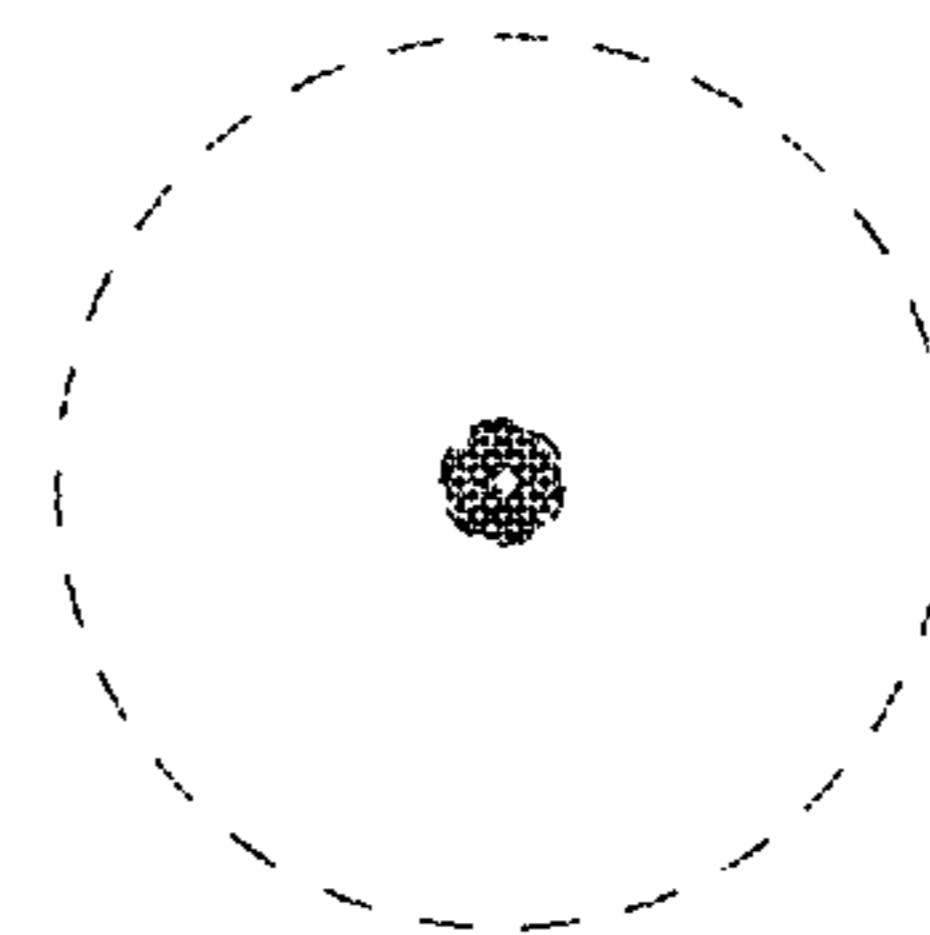


FIG. 4

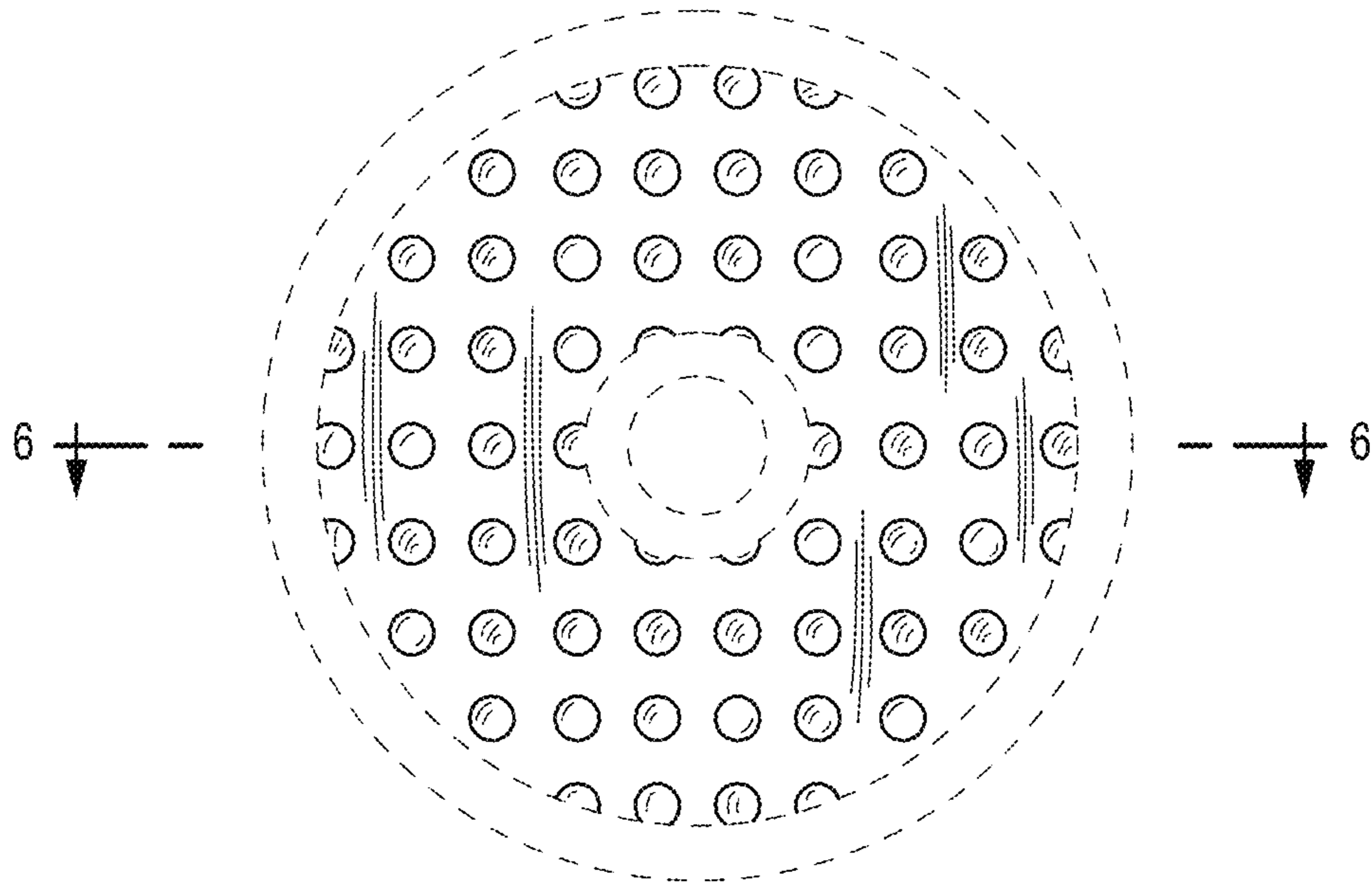


FIG. 5

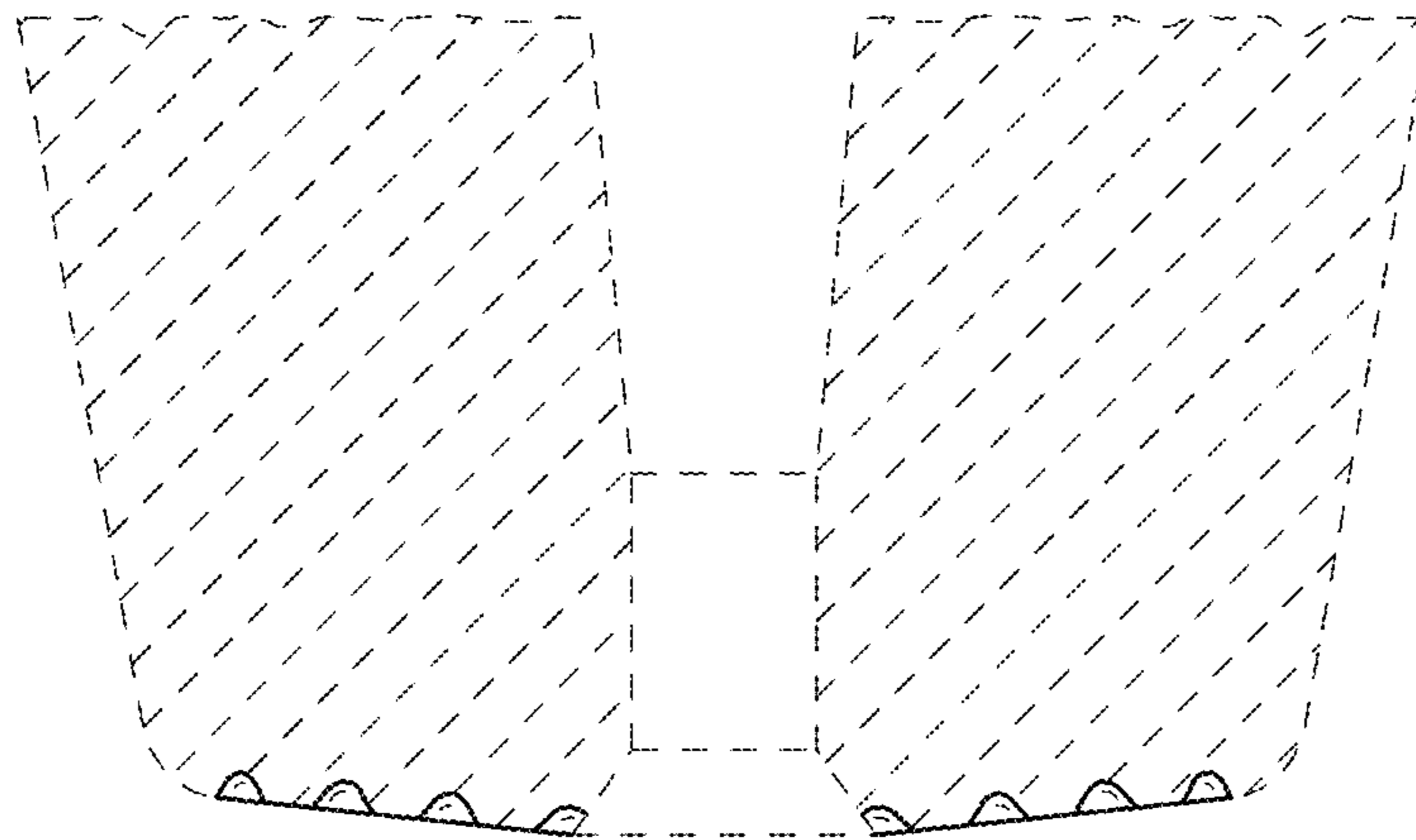


FIG. 6